

Sliver for SFF-TA-1002

TE Internal #: 2336568-1

Internal I/O Connectors, Sliver for SFF-TA-1002, PCB Edge Card, Right Angle, Gen-Z / OCP NIC 3.0, 168 Position, Surface Mount,

Sliver for SFF-TA-1002

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Connectors > PCB Connectors > Internal I/O Connectors



Internal I/O Connector Type: Sliver for SFF-TA-1002

Connector Mates With: PCB Edge Card
PCB Mount Orientation: Right Angle
Industry Standard: Gen-Z, OCP NIC 3.0

Number of Positions: 168

Features

Product Type Features

Internal I/O Connector Type	Sliver for SFF-TA-1002
Connector Mates With	PCB Edge Card
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Powe	2

Number of Rows	2
PCB Mount Orientation	Right Angle
Number of Positions	168

Contact Features

Contact Mating Area Plating Material	Gold
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	1.1 A
Contact Mating Area Plating Material Thickness	.076 µm[3 µin]



Termination Features

Termination Method to Printed Circuit Board	Surface Mount
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	.6 mm[.023 in]
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
Industry Standard	Gen-Z, OCP NIC 3.0

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides



on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts

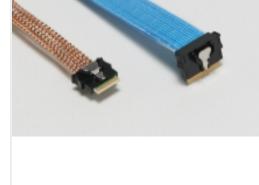






Also in the Series | Sliver for SFF-TA-1002

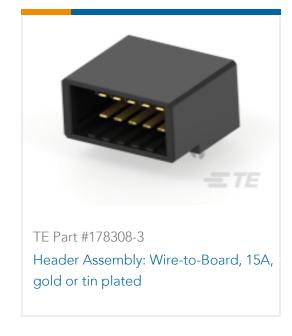




Internal I/O Cable Assemblies(109)



Customers Also Bought

















Documents

CAD Files



3D PDF

3D

Customer View Model

ENG_CVM_CVM_2336568-1_2.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2336568-1_2.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2336568-1_2.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use

Datasheets & Catalog Pages

Sliver Internal Cabled Interconnect Solutions Brochure (Chinese)

Product Specifications

Application Specification

English

Product Environmental Compliance

Product Compliance

English

Product Compliance

English

Agency Approvals

UL Report

English